Amendments To The Claims

Listing of Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

- 1. (Currently Amended) A device <u>for vapor phase deposition of a material onto a substrate</u>, comprising:
 - a base;
 - a metal or metal oxide cladding coated on the base;
- a reservoir defined by the base and the cladding, wherein the reservoir has an opening, and wherein the largest dimension of the opening is less than about 200 nm; and the material for vapor phase deposition is disposed within the reservoir.
- 2. (Original) The device of claim 1, wherein the reservoir comprises a volume removed from the base inside the cladding.
- 3. (Cancel).
- 4. (Currently Amended) The device of claim $\frac{3}{2}$, wherein the material disposed within the reservoir is an organic material.
- 5. (Withdrawn) The device of claim 3, wherein the material disposed within the reservoir is silicon or germanium.
- 6. (Original) The device of claim 1, wherein the cladding is gold.
- 7. (Original) The device of claim 1, wherein the largest dimension of the opening is less than about 100 nm.
- 8. (Original) The device of claim 7, wherein the largest dimension of the opening is about 60 nm or less.

- 9. (Original) The device of claim 1, further comprising a position control apparatus attached to the base.
- 10. (Currently Amended) The device of claim 9, wherein the position control apparatus further comprises emprises a piezoelectric component.
- 11. (Withdrawn) The device of claim 9, wherein the position control apparatus further comprises an atomic force microscope apparatus.
- 12. (Withdrawn) The device of claim 9, wherein the position control apparatus further comprises a near-field scanning optical microscope apparatus.
- 13. (Original) The device of claim 9, further comprising an energy application apparatus coupled to the base.
- 14. (Original) The device of claim 13, wherein the base comprises an optical fiber, and the energy application apparatus comprises a light source optically connected to the optical fiber.
- 15. (Withdrawn) A method of manufacturing a device, comprising: obtaining a base having a tip; coating the tip of the base with a cladding material; removing a portion of the base from under the cladding material to create a reservoir, wherein the reservoir has an opening with a largest diameter of about 200 nm or less.
- 16. (Withdrawn) The method of claim 15, wherein the base is obtained by pulling an optical fiber.
- 17. (Withdrawn) The method of claim 15, wherein the cladding material is a metal.
- 18. (Withdrawn) The method of claim 15, wherein the cladding material is a metal oxide.
- 19. (Withdrawn) The method of claim 15, wherein the opening has a largest diameter of about 100 nm or less.

- 20. (Withdrawn) The method of claim 15, wherein the opening has a largest diameter of about 60 nm or less.
- 21. (Withdrawn) The method of claim 15, wherein the portion of the base is removed by etching.
- 22. (Withdrawn) A method of depositing a material, comprising:

obtaining a base including a reservoir having an opening with a largest dimension less than about 200 nm, wherein a material is disposed within the reservoir, and wherein the reservoir is defined by a part of the base and a cladding on the base;

positioning the opening in the reservoir adjacent to a substrate;

applying energy to the material such that some of the material is expelled through the opening and deposited on the substrate.

- 23. (Withdrawn) The method of claim 22, wherein the base comprises an optical fiber, and the applied energy is light applied to the organic material through the optical fiber.
- 24. (Withdrawn) The method of claim 22, wherein the applied energy is heat.
- 25. (Withdrawn) The method of claim 22, wherein the material is an organic material.
- 26. (Withdrawn) The method of claim 22, wherein the material is silicon or germanium.
- 27. (Withdrawn) The method of claim 22, wherein the material is deposited in a pattern having features with a resolution of less than about 5 nm.
- 28. (Withdrawn) The method of claim 22, wherein the opening is positioned using an atomic force microscope technique, and the base acts as an atomic force microscope tip.
- 29. (Withdrawn) The method of claim 22, wherein the opening is positioned using a near-field scanning optical microscope technique, and the base is used to transmit light for use in the near-field scanning optical microscope technique.

- 30. (Withdrawn) A method of fabricating a device, comprising: obtaining a substrate having a material disposed thereon; using a position control apparatus to position a base adjacent to the material; removing the material adjacent to the base by applying energy through the base.
- 31. (Withdrawn) The method of claim 30, wherein the base is covered with a cladding.
- 32. (Withdrawn) The method of claim 30, wherein the position control apparatus is an atomic force microscope technique, and the base acts as an atomic force microscope tip.
- 33. (Withdrawn) The method of claim 31, wherein the position control apparatus is a near field scanning optical microscope, and the base is used to transmit light for use in the near-field scanning optical microscope.